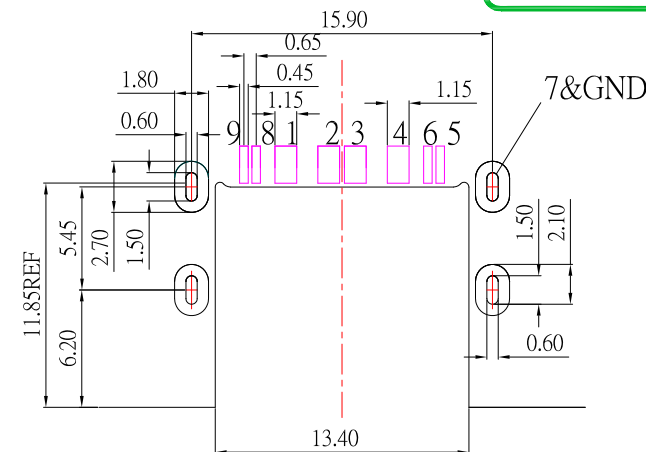
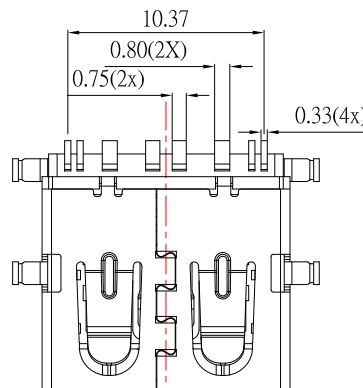
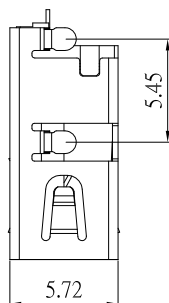
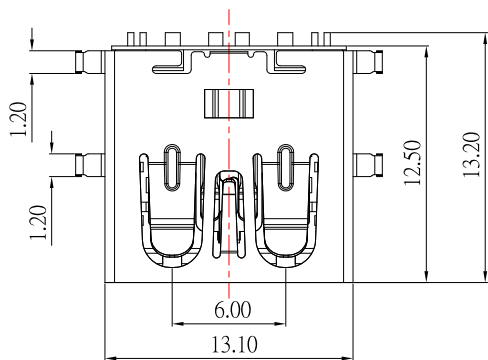
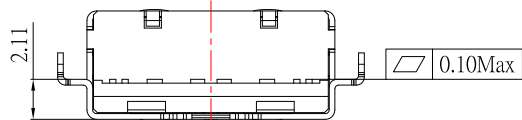




SUA-110M9-32x-S277

鍍層厚度:

Blank	: 1u"
2	: 15u"
3	: 30u"



PCB LAYOUT

NOTE:

1.MATERIAL:

- 1.1 Housing: LCP
- 1.2 Contact: Phosphor Bronze
- 1.3 Shell: SUS

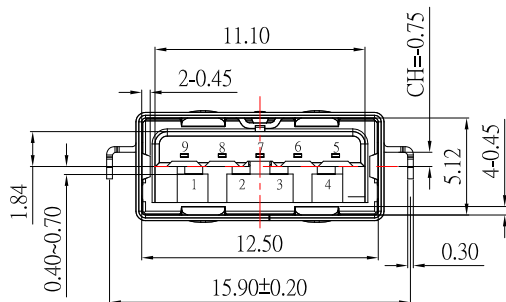
2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 Current Rate: 3.0 A
- 3.2 insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 500V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Mating Force: 8N~20N
- 3.6 Unmating Force: 8N~20N
- 3.7 Operation Temperature: -25°C ~ +85°C

Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield



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TOLERANCE UNLESS OTHERWISE STATED:

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD. ANGEL'S



UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	11/02/23			
CHECKED BY:	DATE	FINISH	MODLE	USB 3.1 10G AF SMT本體長=12.5mm, 板上高2.11 無捲邊
Jacky Chen	11/02/23			
APPROVED BY:	DATE	SCALE	DWG NO.	SUA-110M9-32x-S277
Tony Kao	11/02/23	1 : 1	PART NO.	SUA-110M9-32x-S277
		SHEET NO.	1 of 1	

ITEM NO.	DESCRIPTION	DRAWN	DATE